

DUAL DAMASCENE ANTI-FUSE WITH VIA BEFORE WIRE

ABSTRACT OF THE DISCLOSURE

5 An interconnect structure in which a patterned anti-fuse
material is formed therein comprising: a substrate having
a first level of electrically conductive features; a
patterned anti-fuse material formed on said substrate,
wherein said patterned anti-fuse material includes an
opening to at least one of said first level of
10 electrically conductive features; a patterned interlevel
dielectric material formed on said patterned anti-fuse
material, wherein said patterned interlevel dielectric
includes vias, as least one of said vias includes a via
space; and a second level of electrically conductive
features formed in said vias and via spaces.